

ABSTRACT OF THE DISCLOSURE

An EMI shielding structure for a printed circuit board for shielding wiring circuit traces on a plurality of circuit trace layers applied on a plurality of printed circuit board layers and electrically isolated there between by the printed circuit board layers. The EMI shielding structure has a printed circuit board multi-layer structure, characterized by: a trench having a rim about an opening of the trench at a top printed circuit board layer and said trench extending through a plurality of printed circuit board layers to a grounding plane exposing said grounding plane. Said trench having an interior wall with a conductive plating material applied over said wall and said trench having a length greater than two times a breadth of said trench and said wall vertically extends around the perimeter of the printed circuit board and said plating electrically connects to said exposed ground plane and wraps over and laterally extends from said rim forming a lip.